

Megaposit SPR 220-3.0 – run sheet

Rohm and Haas Electronic Materials

nanyte.com/photoresists/spr220-3 · last updated 2026-07-26

Thickness: 2.3–4.6 μm

Softbake: 115 °C · 1.5 min · hotplate

Exposure dose: 310 mJ/cm² @ 365 nm

Post-exposure bake: 115 °C · 1.5 min

Develop: Developer MF-24A (0.24N MIF – metal-ion-free TMAH developer) · Dilution 0.24N (MF-24A is the 0.24N-normality developer in Rohm and Haas's MF line; SPR220 is "optimized for 0.24N developers", with 0.26N (MF-26A) offered as an alternative for thicker films or high-throughput processes) · Time 60 s · Method puddle